

Please replace the paragraph beginning at page 91, line 2, with the following rewritten paragraph:

A2 The solder paste filling pressure detected by the pressure sensor 51 is patterned as waveform data indicated by, for example, K in Fig. 38B by a waveform generating section 61 of the control unit 24 and transmitted to an operating section 62. The operating section 62 refers to a database 64 that has preparatorily stored normal waveform data, or the information, which is the pressure waveform of the solder paste and becomes a criterion of decision, and determines whether or not the waveform of the measured filling pressure of the solder paste 7 is normal by comparison.

IN THE CLAIMS:

Kindly amend the following claims:

1.(Amended) A solder paste printing apparatus for printing a solder paste supplied onto a surface of a printing mask where an opening is formed by moving a squeegee on the surface in a printing direction on a circuit-forming body placed on a back surface of the printing mask via the opening, the device comprising:

an elongated pressurizing member that has an axial direction extended roughly parallel to an axial direction of the squeegee and is able to form between the pressurizing member and the printing mask a first gap through which the solder paste can pass in a direction opposite to the printing direction of the squeegee during solder paste printing and is arranged so as to form between the pressurizing member and the squeegee a second gap through which the solder paste can pass from the first gap toward the squeegee side, the pressurizing member being provided in a vicinity of an edge of the squeegee, whereby a pressure toward the printing mask is applied to the solder paste by the pressurizing member when the solder paste passes through the first gap located between the pressurizing member and the printing mask during the solder paste printing.